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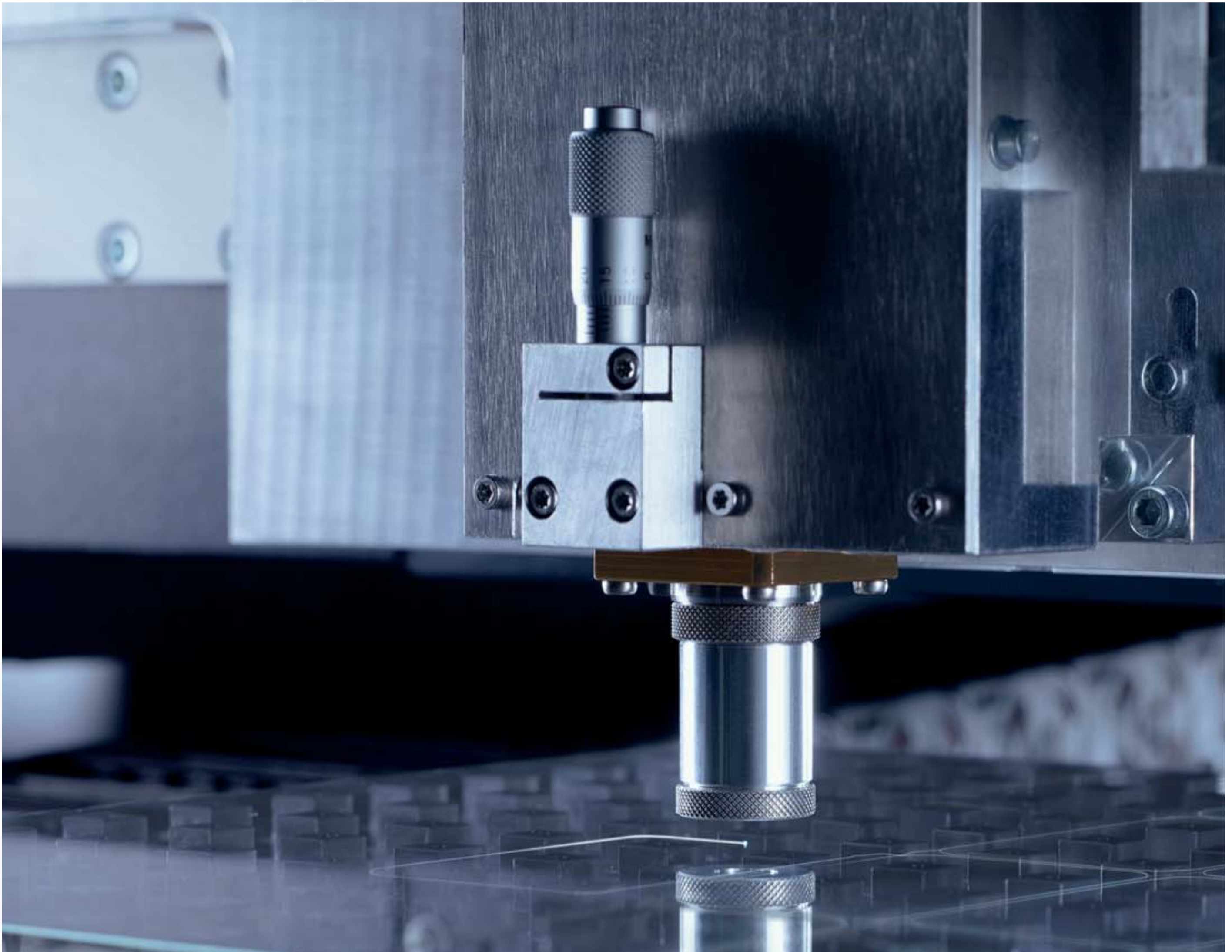
passion for efficiency

DLC SERIES
LASER PLATFORMS FOR ELECTRONICS



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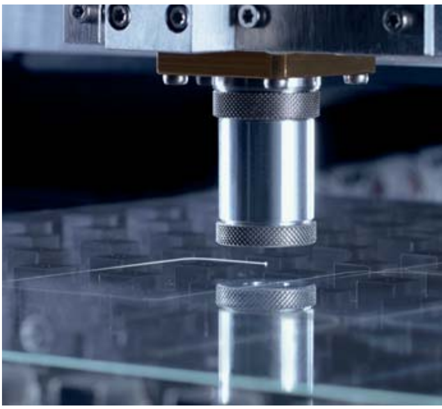
Laser Platforms for Electronics



TECHNICAL SPECIFICATIONS

DLC SERIES		
Dimensions (L x W x H)	2,900 mm x 2,800 mm x 2,700 mm	
Weight	5,000 - 5,500 kg	
Power supply	200 - 480 V	
Compressed dry air	6 - 7 bar	
Cooling Water	5 - 20 l/min	
Working area	X-axis 1,300 mm Y-axis 1,400 mm up to GEN 5	
Accuracy	$< \pm 20\ \mu m$ absolute $< \pm 10\ \mu m$ repeatability	
Available laser sources	Wave length	1,030 nm
	Pulse	ps
Laser spot size	2 μm	
Beam delivery	Fixed optics	
Safety	CE	

PROCESS AND SYSTEM VALUES	
Material	single glass (unstrengthened and strengthened glass)
Material thicknesses	<1.8 mm
Sidewall roughness values	$\sim 0.4\ \mu m$
Maximum product size	up to Gen 5
Cutting speed	up to 1 m/s
Creation of Inner contour	down to 3 mm possible

PROCESS AND SYSTEM LIMITATIONS
No coating on top side allowed
For chemically strengthened glass a camera system for alignment detection can be used (25 μm accuracy)

FEATURES

- *Universal cutting system*
- *Highly modular system design*
- *Fast manufacturing*
- *High volumes and quick ramp-up*
- *Highly accurate system*
- *Standalone and line integrable system*
- *Linear / free forms*
- *Up to 2 x scanner heads*
- *Up to 2 x fixed optical process heads*

OPTIONAL

- *Fully automatic handling (Production)*
- *Semi-automatic handling (R&D)*
- *MES interface*
- *Integrated process metrology*
- *Import of CAD files (e.g. DXF, DWG)*
- *Vision system*

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